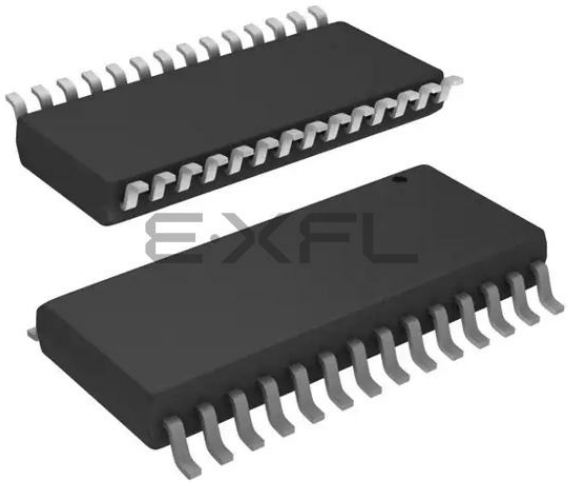

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 17x10b; D/A 1x5b, 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1716-e-so

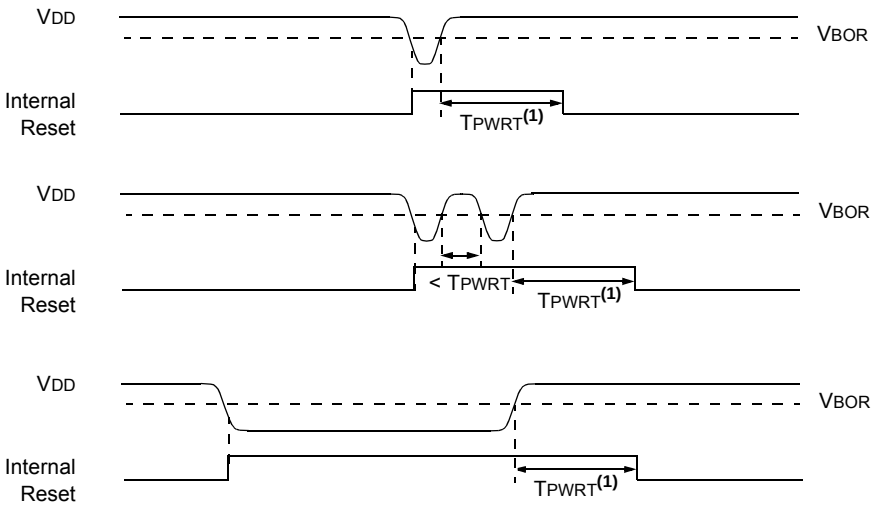
TABLE 3-6: PIC16(L)F1716 MEMORY MAP, BANK 8-23

BANK 8		BANK 9		BANK 10		BANK 11		BANK 12		BANK 13		BANK 14		BANK 15	
400h	Core Registers (Table 3-2)	480h	Core Registers (Table 3-2)	500h	Core Registers (Table 3-2)	580h	Core Registers (Table 3-2)	600h	Core Registers (Table 3-2)	680h	Core Registers (Table 3-2)	700h	Core Registers (Table 3-2)	780h	Core Registers (Table 3-2)
40Bh		48Bh		50Bh		58Bh		60Bh		68Bh		70Bh		78Bh	
40Ch	—	48Ch	—	50Ch	—	58Ch	—	60Ch	—	68Ch	—	70Ch	—	78Ch	—
40Dh	—	48Dh	—	50Dh	—	58Dh	—	60Dh	—	68Dh	—	70Dh	—	78Dh	—
40Eh	—	48Eh	—	50Eh	—	58Eh	—	60Eh	—	68Eh	—	70Eh	—	78Eh	—
40Fh	—	48Fh	—	50Fh	—	58Fh	—	60Fh	—	68Fh	—	70Fh	—	78Fh	—
410h	—	490h	—	510h	—	590h	—	610h	—	690h	—	710h	—	790h	—
411h	—	491h	—	511h	OPA1CON	591h	—	611h	—	691h	COG1PHR	711h	—	791h	—
412h	—	492h	—	512h	—	592h	—	612h	—	692h	COG1PHF	712h	—	792h	—
413h	—	493h	—	513h	—	593h	—	613h	—	693h	COG1BLKR	713h	—	793h	—
414h	—	494h	—	514h	—	594h	—	614h	—	694h	COG1BLKF	714h	—	794h	—
415h	TMR4	495h	—	515h	OPA2CON	595h	—	615h	—	695h	COG1DBR	715h	—	795h	—
416h	PR4	496h	—	516h	—	596h	—	616h	—	696h	COG1DBF	716h	—	796h	—
417h	T4CON	497h	—	517h	—	597h	—	617h	PWM3DCL	697h	COG1CON0	717h	—	797h	—
418h	—	498h	NCO1ACCL	518h	—	598h	—	618h	PWM3DCH	698h	COG1CON1	718h	—	798h	—
419h	—	499h	NCO1ACCH	519h	—	599h	—	619h	PWM3CON	699h	COG1RIS	719h	—	799h	—
41Ah	—	49Ah	NCO1ACCU	51Ah	—	59Ah	—	61Ah	PWM4DCL	69Ah	COG1RSIM	71Ah	—	79Ah	—
41Bh	—	49Bh	NCO1INCL	51Bh	—	59Bh	—	61Bh	PWM4DCH	69Bh	COG1FIS	71Bh	—	79Bh	—
41Ch	TMR6	49Ch	NCO1INCH	51Ch	—	59Ch	—	61Ch	PWM4CON	69Ch	COG1FSIM	71Ch	—	79Ch	—
41Dh	PR6	49Dh	NCO1INCU	51Dh	—	59Dh	—	61Dh	—	69Dh	COG1ASD0	71Dh	—	79Dh	—
41Eh	T6CON	49Eh	NCO1CON	51Eh	—	59Eh	—	61Eh	—	69Eh	COG1ASD1	71Eh	—	79Eh	—
41Fh	—	49Fh	NCO1CLK	51Fh	—	59Fh	—	61Fh	—	69Fh	COG1STR	71Fh	—	79Fh	—
420h	General Purpose Register 80 Bytes	4A0h	General Purpose Register 80 Bytes	520h	General Purpose Register 80 Bytes	5A0h	General Purpose Register 80 Bytes	620h	General Purpose Register 48 Bytes	6A0h	Unimplemented Read as '0'	720h	Unimplemented Read as '0'	7A0h	Unimplemented Read as '0'
46Fh		4EFh		56Fh		5EFh		64Fh	Unimplemented Read as '0'	6EFh		76Fh		7EFh	
470h	Accesses 70h – 7Fh	4F0h	Accesses 70h – 7Fh	570h	Accesses 70h – 7Fh	5F0h	Accesses 70h – 7Fh	670h	Accesses 70h – 7Fh	6F0h	Accesses 70h – 7Fh	770h	Accesses 70h – 7Fh	7F0h	Accesses 70h – 7Fh
47Fh		4FFh		57Fh		5FFh		67Fh		6FFh		77Fh		7FFh	

BANK 16		BANK 17		BANK 18		BANK 19		BANK 20		BANK 21		BANK 22		BANK 23	
800h	Core Registers (Table 3-2)	880h	Core Registers (Table 3-2)	900h	Core Registers (Table 3-2)	980h	Core Registers (Table 3-2)	A00h	Core Registers (Table 3-2)	A80h	Core Registers (Table 3-2)	B00h	Core Registers (Table 3-2)	B80h	Core Registers (Table 3-2)
80Bh		88Bh		90Bh		98Bh		A0Bh		A8Bh		B0Bh		B8Bh	
80Ch	Unimplemented Read as '0'	88Ch	Unimplemented Read as '0'	90Ch	Unimplemented Read as '0'	98Ch	Unimplemented Read as '0'	A0Ch	Unimplemented Read as '0'	A8Ch	Unimplemented Read as '0'	B0Ch	Unimplemented Read as '0'	B8Ch	Unimplemented Read as '0'
86Fh		8EFh		96Fh		9EFh		A6Fh		AEFh		B6Fh		BEFh	
870h	Accesses 70h – 7Fh	8F0h	Accesses 70h – 7Fh	970h	Accesses 70h – 7Fh	9F0h	Accesses 70h – 7Fh	A70h	Accesses 70h – 7Fh	AF0h	Accesses 70h – 7Fh	B70h	Accesses 70h – 7Fh	BF0h	Accesses 70h – 7Fh
87Fh		8FFh		97Fh		9FFh		A7Fh		AFFh		B7Fh		BFFh	

Legend: = Unimplemented data memory locations, read as '0'.

FIGURE 5-2: BROWN-OUT SITUATIONS



Note 1: TPWRT delay only if $\overline{\text{PWRTE}}$ bit is programmed to '0'.

5.3 Register Definitions: BOR Control

REGISTER 5-1: BORCON: BROWN-OUT RESET CONTROL REGISTER

R/W-1/u	R/W-0/u	U-0	U-0	U-0	U-0	U-0	R-q/u
SBOREN	BORFS(1)	—	—	—	—	—	BORRDY
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7 **SBOREN:** Software Brown-out Reset Enable bit
If BOREN <1:0> in Configuration Words ≠ 01:
SBOREN is read/write, but has no effect on the BOR.
If BOREN <1:0> in Configuration Words = 01:
1 = BOR Enabled
0 = BOR Disabled

bit 6 **BORFS:** Brown-out Reset Fast Start bit(1)
If BOREN<1:0> = 11 (Always on) or BOREN<1:0> = 00 (Always off)
BORFS is Read/Write, but has no effect.
If BOREN <1:0> = 10 (Disabled in Sleep) or BOREN<1:0> = 01 (Under software control):
1 = Band gap is forced on always (covers sleep/wake-up/operating cases)
0 = Band gap operates normally, and may turn off

bit 5-1 **Unimplemented:** Read as '0'

bit 0 **BORRDY:** Brown-out Reset Circuit Ready Status bit
1 = The Brown-out Reset circuit is active
0 = The Brown-out Reset circuit is inactive

Note 1: BOREN<1:0> bits are located in Configuration Words.

8.0 POWER-DOWN MODE (SLEEP)

The Power-down mode is entered by executing a SLEEP instruction.

Upon entering Sleep mode, the following conditions exist:

1. WDT will be cleared but keeps running, if enabled for operation during Sleep.
2. $\overline{PD}$ bit of the STATUS register is cleared.
3. $\overline{TO}$ bit of the STATUS register is set.
4. CPU clock is disabled.
5. 31 kHz LFINTOSC is unaffected and peripherals that operate from it may continue operation in Sleep.
6. Timer1 and peripherals that operate from Timer1 continue operation in Sleep when the Timer1 clock source selected is:
   - LFINTOSC
   - T1CKI
   - Secondary oscillator
7. ADC is unaffected, if the dedicated FRC oscillator is selected.
8. I/O ports maintain the status they had before SLEEP was executed (driving high, low or high-impedance).
9. Resets other than WDT are not affected by Sleep mode.

Refer to individual chapters for more details on peripheral operation during Sleep.

To minimize current consumption, the following conditions should be considered:

- I/O pins should not be floating
- External circuitry sinking current from I/O pins
- Internal circuitry sourcing current from I/O pins
- Current draw from pins with internal weak pull-ups
- Modules using 31 kHz LFINTOSC
- Modules using secondary oscillator

I/O pins that are high-impedance inputs should be pulled to V_{DD} or V_{SS} externally to avoid switching currents caused by floating inputs.

Examples of internal circuitry that might be sourcing current include modules such as the DAC and FVR modules. See **Section 22.0 “Operational Amplifier (OPA) Modules”** and **Section 14.0 “Fixed Voltage Reference (FVR)”** for more information on these modules.

8.1 Wake-up from Sleep

The device can wake-up from Sleep through one of the following events:

1. External Reset input on $\overline{MCLR}$ pin, if enabled
2. BOR Reset, if enabled
3. POR Reset
4. Watchdog Timer, if enabled
5. Any external interrupt
6. Interrupts by peripherals capable of running during Sleep (see individual peripheral for more information)

The first three events will cause a device Reset. The last three events are considered a continuation of program execution. To determine whether a device Reset or wake-up event occurred, refer to **Section 5.12 “Determining the Cause of a Reset”**.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is prefetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be enabled. Wake-up will occur regardless of the state of the GIE bit. If the GIE bit is disabled, the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is enabled, the device executes the instruction after the SLEEP instruction, the device will then call the Interrupt Service Routine. In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

The WDT is cleared when the device wakes up from Sleep, regardless of the source of wake-up.

8.2 Low-Power Sleep Mode

The PIC16F1713/6 device contains an internal Low Dropout (LDO) voltage regulator, which allows the device I/O pins to operate at voltages up to 5.5V while the internal device logic operates at a lower voltage. The LDO and its associated reference circuitry must remain active when the device is in Sleep mode. The PIC16F1713/6 allows the user to optimize the operating current in Sleep, depending on the application requirements.

A Low-Power Sleep mode can be selected by setting the VREGPM bit of the VREGCON register. With this bit set, the LDO and reference circuitry are placed in a low-power state when the device is in Sleep.

8.2.1 SLEEP CURRENT VS. WAKE-UP TIME

In the default operating mode, the LDO and reference circuitry remain in the normal configuration while in Sleep. The device is able to exit Sleep mode quickly since all circuits remain active. In Low-Power Sleep mode, when waking up from Sleep, an extra delay time is required for these circuits to return to the normal configuration and stabilize.

The Low-Power Sleep mode is beneficial for applications that stay in Sleep mode for long periods of time. The normal mode is beneficial for applications that need to wake from Sleep quickly and frequently.

8.2.2 PERIPHERAL USAGE IN SLEEP

Some peripherals that can operate in Sleep mode will not operate properly with the Low-Power Sleep mode selected. The Low-Power Sleep mode is intended for use only with the following peripherals:

- Brown-out Reset (BOR)
- Watchdog Timer (WDT)
- External interrupt pin/Interrupt-on-change pins
- Timer1 (with external clock source < 100 kHz)

Note:	The PIC16LF1713/6 does not have a configurable Low-Power Sleep mode. PIC16LF1713/6 is an unregulated device and is always in the lowest power state when in Sleep, with no wake-up time penalty. This device has a lower maximum V_{DD} and I/O voltage than the PIC16F1713/6. See **Section 34.0 "Electrical Specifications"** for more information.

FIGURE 18-2: SIMPLIFIED COG BLOCK DIAGRAM (STEERED PWM MODE, GXMD = 0)

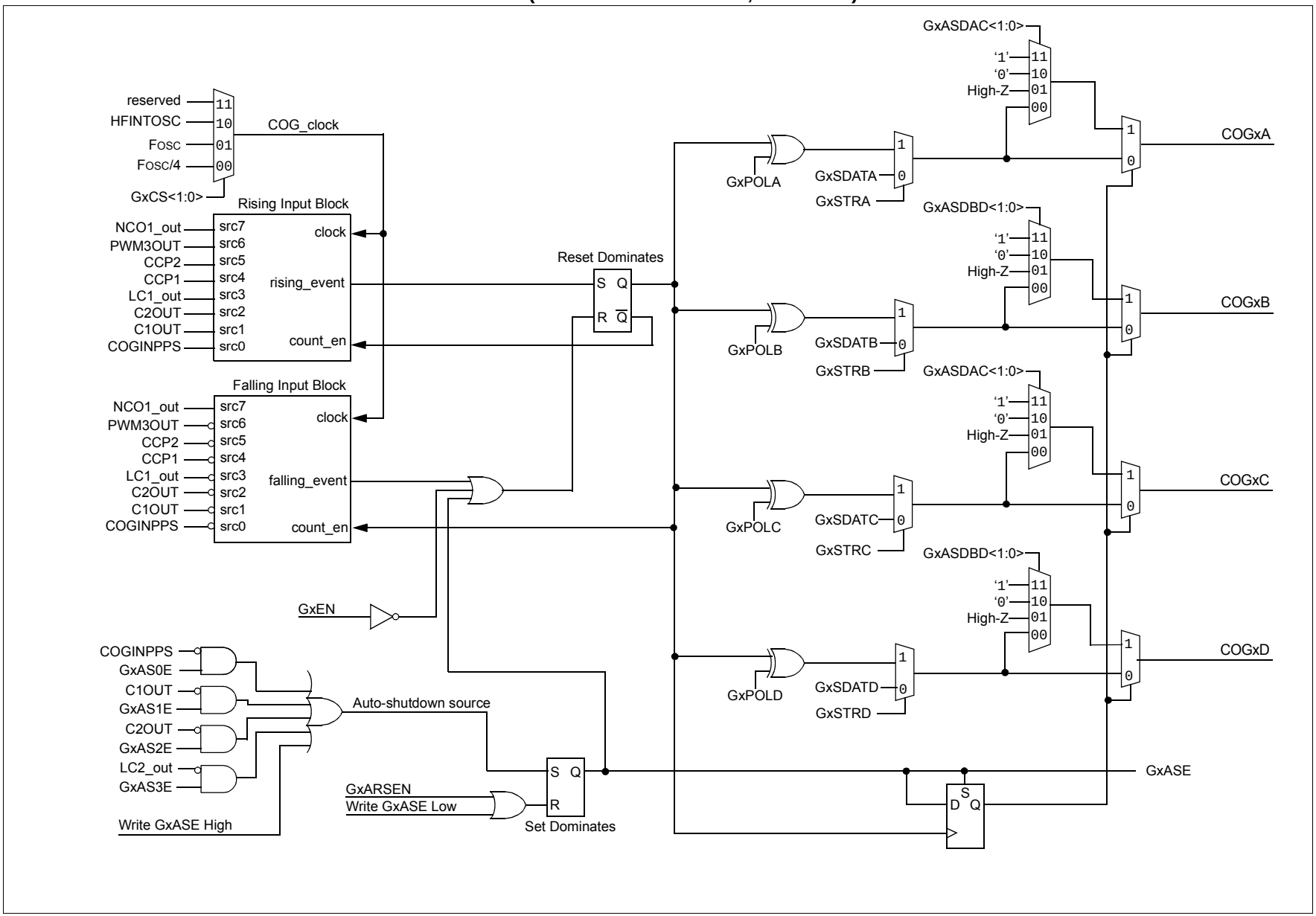


FIGURE 18-12: FULL-BRIDGE FORWARD MODE COG OPERATION WITH CCP1

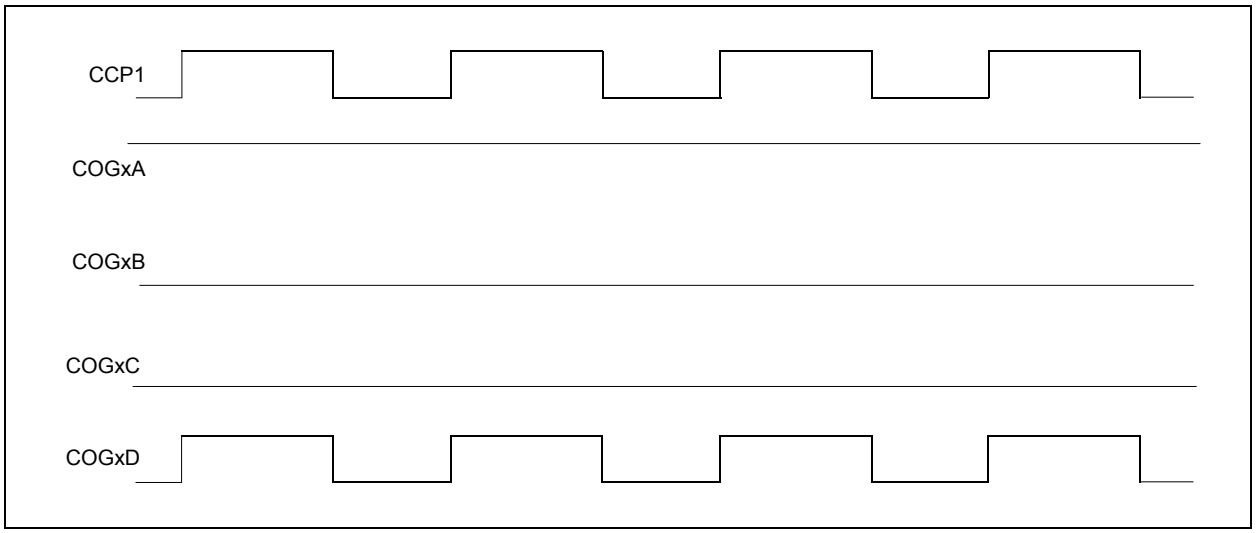
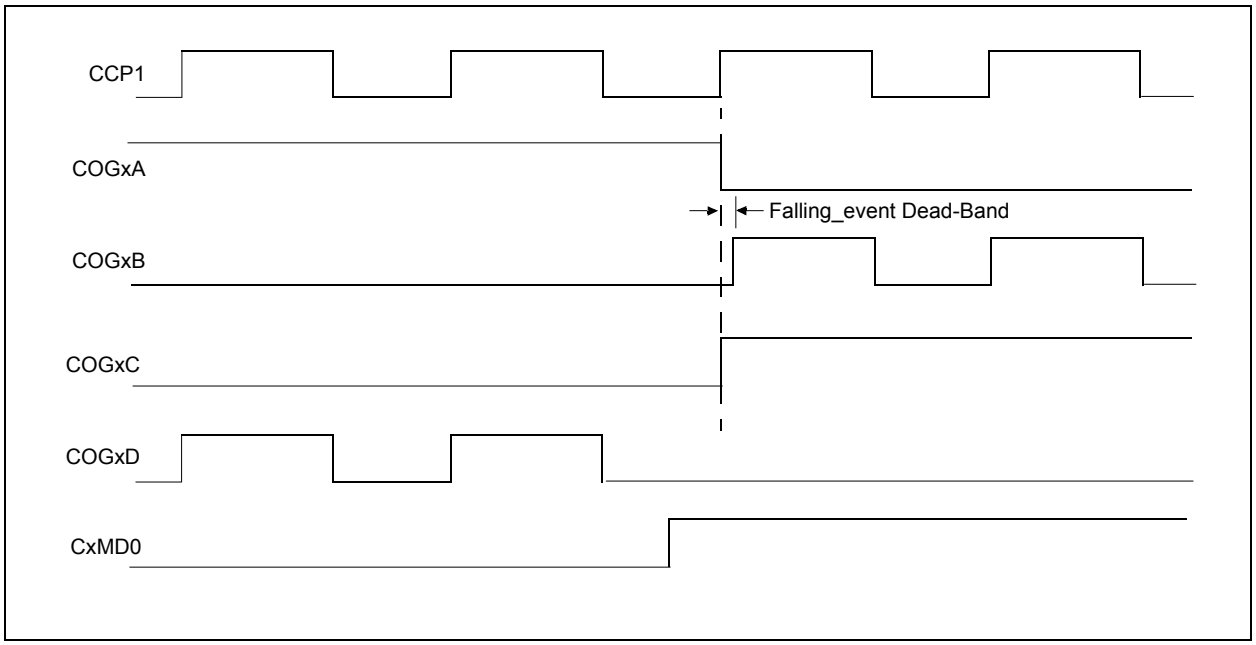


FIGURE 18-13: FULL-BRIDGE MODE COG OPERATION WITH CCP1 AND DIRECTION CHANGE



REGISTER 18-3: COGxRIS: COG RISING EVENT INPUT SELECTION REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
GxRIS7	GxRIS6	GxRIS5	GxRIS4	GxRIS3	GxRIS2	GxRIS1	GxRIS0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7 **GxRIS7:** COGx Rising Event Input Source 7 Enable bit
1 = NCO1_out is enabled as a rising event input
0 = NCO1_out has no effect on the rising event

bit 6 **GxRIS6:** COGx Rising Event Input Source 6 Enable bit
1 = PWM3 output is enabled as a rising event input
0 = PWM3 has no effect on the rising event

bit 5 **GxRIS5:** COGx Rising Event Input Source 5 Enable bit
1 = CCP2 output is enabled as a rising event input
0 = CCP2 output has no effect on the rising event

bit 4 **GxRIS4:** COGx Rising Event Input Source 4 Enable bit
1 = CCP1 is enabled as a rising event input
0 = CCP1 has no effect on the rising event

bit 3 **GxRIS3:** COGx Rising Event Input Source 3 Enable bit
1 = CLC1 output is enabled as a rising event input
0 = CLC1 output has no effect on the rising event

bit 2 **GxRIS2:** COGx Rising Event Input Source 2 Enable bit
1 = Comparator 2 output is enabled as a rising event input
0 = Comparator 2 output has no effect on the rising event

bit 1 **GxRIS1:** COGx Rising Event Input Source 1 Enable bit
1 = Comparator 1 output is enabled as a rising event input
0 = Comparator 1 output has no effect on the rising event

bit 0 **GxRIS0:** COGx Rising Event Input Source 0 Enable bit
1 = Pin selected with COGxPPS control register is enabled as rising event input
0 = Pin selected with COGxPPS control has no effect on the rising event

REGISTER 18-14: COGxPHR: COG RISING EDGE PHASE DELAY COUNT REGISTER

U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	GxPHR<5:0>					
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	q = Value depends on condition

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **GxPHR<5:0>:** Rising Edge Phase Delay Count Value bits
= Number of COGx clock periods to delay rising edge event

REGISTER 18-15: COGxPHF: COG FALLING EDGE PHASE DELAY COUNT REGISTER

U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	GxPHF<5:0>					
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	q = Value depends on condition

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **GxPHF<5:0>:** Falling Edge Phase Delay Count Value bits
= Number of COGx clock periods to delay falling edge event

REGISTER 19-3: CLCxSEL0: GENERIC CLCx DATA 1 SELECT REGISTER

U-0	U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	—	LCxD1S<4:0>				
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-5 **Unimplemented:** Read as ‘0’

bit 4-0 **LCxD1S<4:0>:** CLCx Data1 Input Selection bits
See Table 19-1.

REGISTER 19-4: CLCxSEL1: GENERIC CLCx DATA 2 SELECT REGISTER

U-0	U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	—	LCxD2S<4:0>				
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-5 **Unimplemented:** Read as ‘0’

bit 4-0 **LCxD2S<4:0>:** CLCx Data 2 Input Selection bits
See Table 19-1.

REGISTER 19-5: CLCxSEL2: GENERIC CLCx DATA 3 SELECT REGISTER

U-0	U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
—	—	—	LCxD3S<4:0>				
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-5 **Unimplemented:** Read as ‘0’

bit 4-0 **LCxD3S<4:0>:** CLCx Data 3 Input Selection bits
See Table 19-1.

21.4 ADC Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 21-4. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), refer to Figure 21-4. **The maximum recommended impedance for analog sources is 10 kΩ.** As the source impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an ADC acquisition must be done before the conversion can be started. To calculate the minimum acquisition time, Equation 21-1 may be used. This equation assumes that 1/2 LSb error is used (1,024 steps for the ADC). The 1/2 LSb error is the maximum error allowed for the ADC to meet its specified resolution.

EQUATION 21-1: ACQUISITION TIME EXAMPLE

Assumptions: $Temperature = 50°C$ *and external impedance of* $10k\Omega$ *5.0V* V_{DD}

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Hold Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$
$$= 2\mu s + T_C + [(Temperature - 25°C)(0.05\mu s/°C)]$$

The value for T_C *can be approximated with the following equations:*

$$V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) = V_{CHOLD}$$;[1] V_{CHOLD} *charged to within 1/2 lsb*

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{CHOLD}$$;[2] V_{CHOLD} *charge response to* $V_{APPLIED}$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right)$$;combining [1] and [2]

Note: Where n = number of bits of the ADC.

Solving for T_C*:*

$$T_C = -C_{HOLD}(R_{IC} + R_{SS} + R_S)\ ln(1/2047)$$
$$= -10pF(1k\Omega + 7k\Omega + 10k\Omega)\ ln(0.0004885)$$
$$= 1.37\mu s$$

Therefore:

$$T_{ACQ} = 2\mu s + 892ns + [(50°C - 25°C)(0.05\mu s/°C)]$$
$$= 4.62\mu s$$

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

FIGURE 23-1: DIGITAL-TO-ANALOG CONVERTER BLOCK DIAGRAM

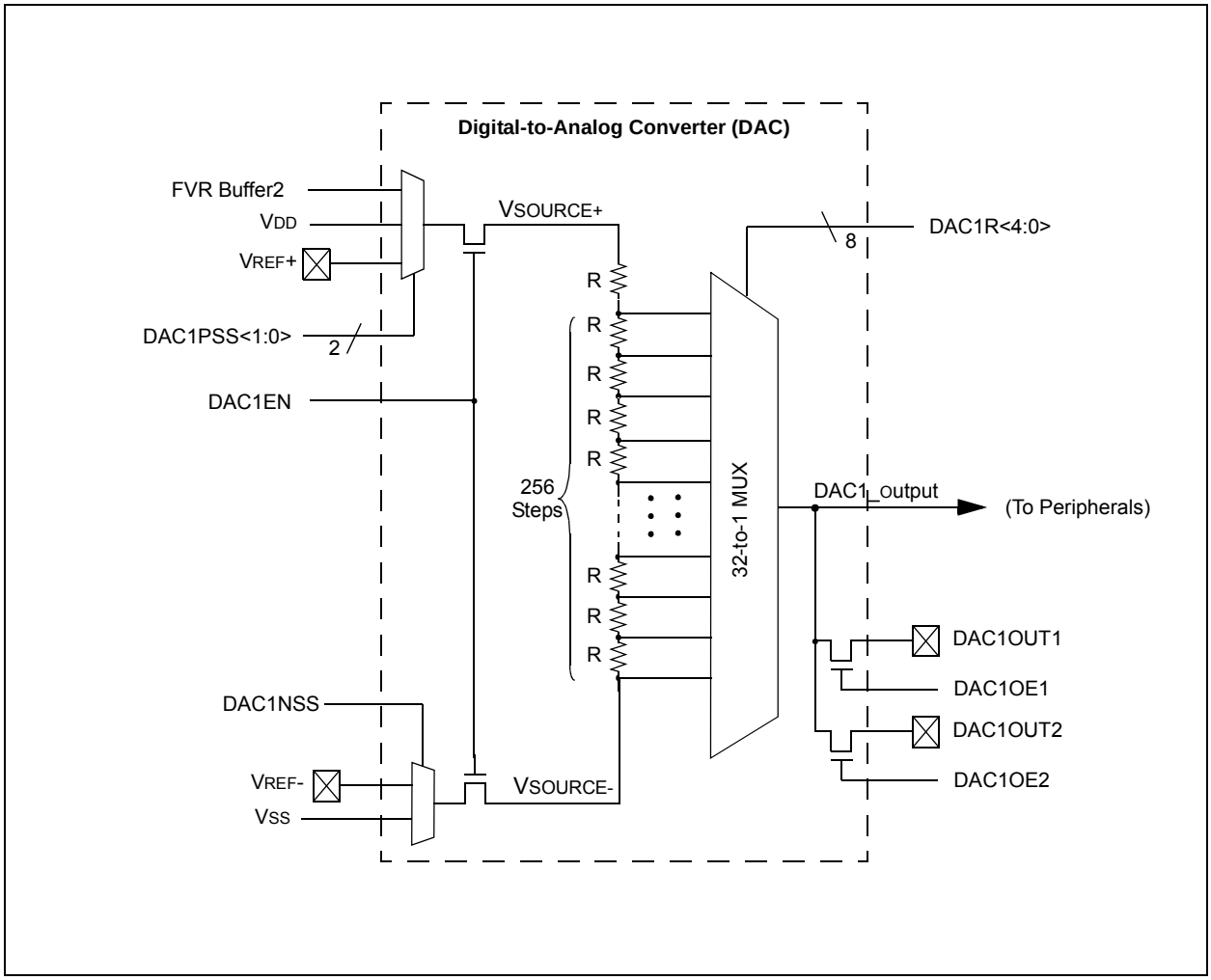
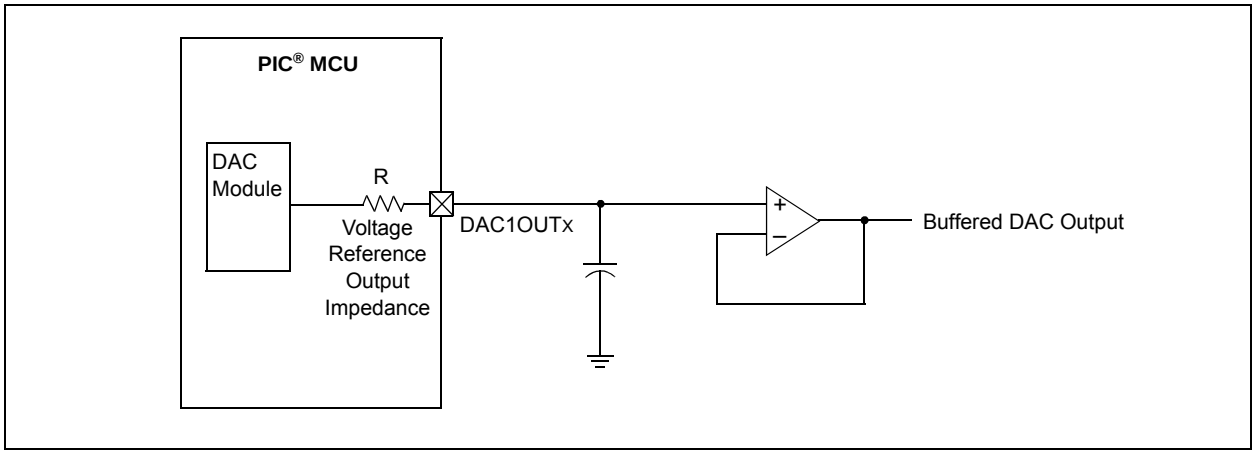


FIGURE 23-2: VOLTAGE REFERENCE OUTPUT BUFFER EXAMPLE



28.9 Register Definitions: ZCD Control

REGISTER 28-1: ZCDxCON: ZERO-CROSS DETECTION CONTROL REGISTER

R/W-0/0	U-0	R-x/x	R/W-0/0	U-0	U-0	R/W-0/0	R/W-0/0
ZCDxEN	—	ZCDxOUT	ZCDxPOL	—	—	ZCDxINTP	ZCDxINTN
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = value depends on configuration bits

bit 7 **ZCDxEN:** Zero-Cross Detection Enable bit(1)
- 1 = Zero-cross detect is enabled. ZCD pin is forced to output to source and sink current.
- 0 = Zero-cross detect is disabled. ZCD pin operates according to PPS and TRIS controls.

bit 6 **Unimplemented:** Read as '0'

bit 5 **ZCDxOUT:** Zero-Cross Detection Logic Level bit

ZCDxPOL bit = 0:
- 1 = ZCD pin is sinking current
- 0 = ZCD pin is sourcing current

ZCDxPOL bit = 1:
- 1 = ZCD pin is sourcing current
- 0 = ZCD pin is sinking current

bit 4 **ZCDxPOL:** Zero-Cross Detection Logic Output Polarity bit
- 1 = ZCD logic output is inverted
- 0 = ZCD logic output is not inverted

bit 3-2 **Unimplemented:** Read as '0'

bit 1 **ZCDxINTP:** Zero-Cross Positive Edge Interrupt Enable bit
- 1 = ZCDIF bit is set on low-to-high ZCDx_output transition
- 0 = ZCDIF bit is unaffected by low-to-high ZCDx_output transition

bit 0 **ZCDxINTN:** Zero-Cross Negative Edge Interrupt Enable bit
- 1 = ZCDIF bit is set on high-to-low ZCDx_output transition
- 0 = ZCDIF bit is unaffected by high-to-low ZCDx_output transition

Note 1: The ZCDxEN bit has no effect when the ZCDDIS Configuration bit is cleared.

TABLE 28-1: SUMMARY OF REGISTERS ASSOCIATED WITH THE ZCD MODULE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
PIE3	—	—	COGIE	ZCDIE	—	—	—	—	86
PIR3	—	—	CWGIF	ZCDIF	—	—	—	—	89
ZCD1CON	ZCD1EN	—	ZCD1OUT	ZCD1POL	—	—	ZCD1INTP	ZCD1INTN	276

Legend: — = unimplemented, read as '0'. Shaded cells are unused by the ZCD module.

TABLE 28-2: SUMMARY OF CONFIGURATION WORD WITH THE ZCD MODULE

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG2	13:8	—	—	LVP	$\overline{\text{DEBUG}}$	$\overline{\text{LPBOR}}$	BORV	STVREN	PLLEN	49
	7:0	ZCDDIS	—	—	—	—	—	WRT<1:0>		

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by the ZCD module.

FIGURE 30-9: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 0)

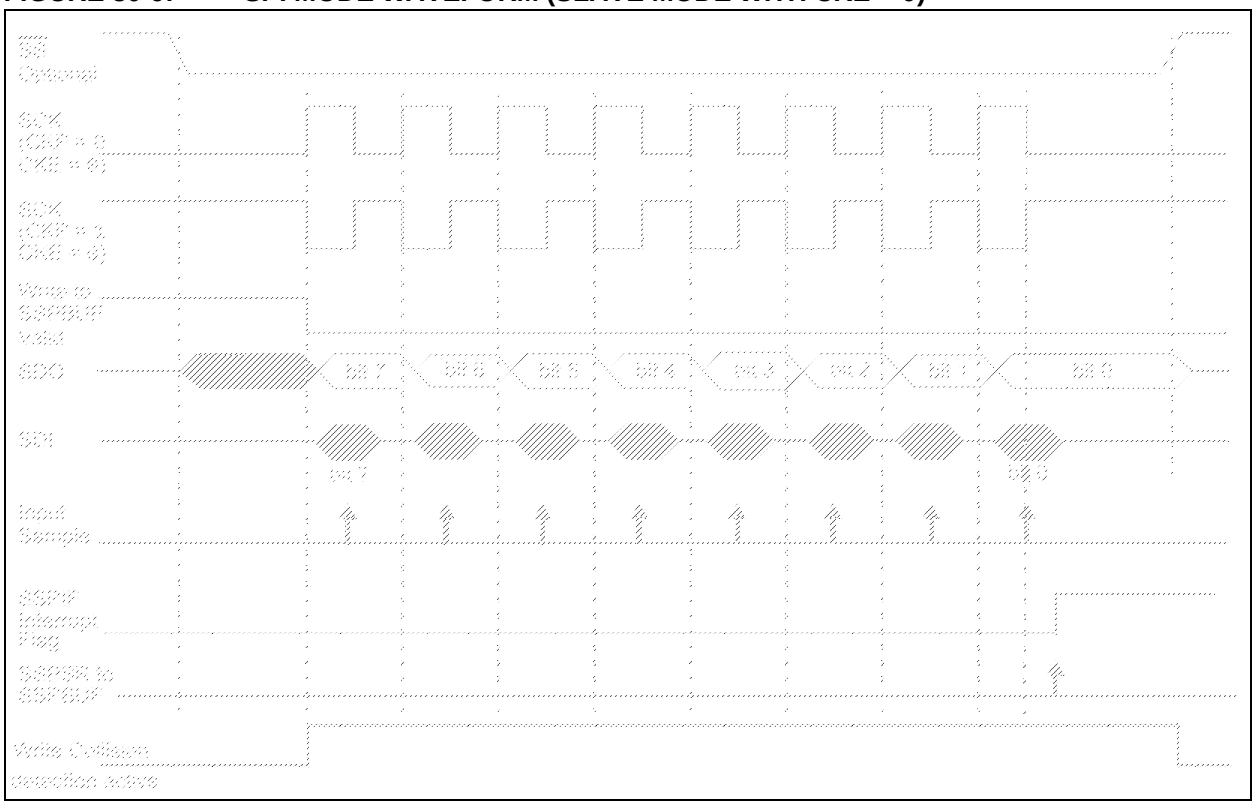


FIGURE 30-10: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 1)

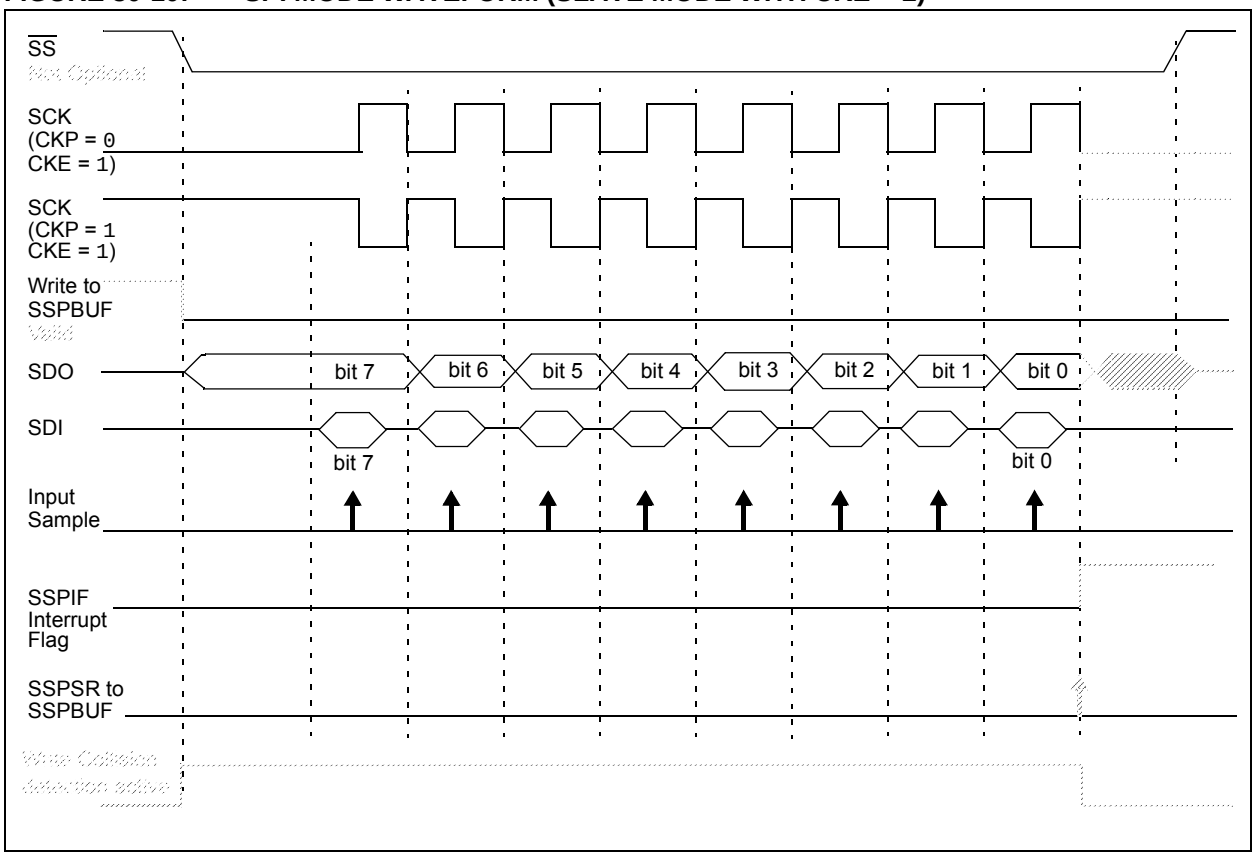
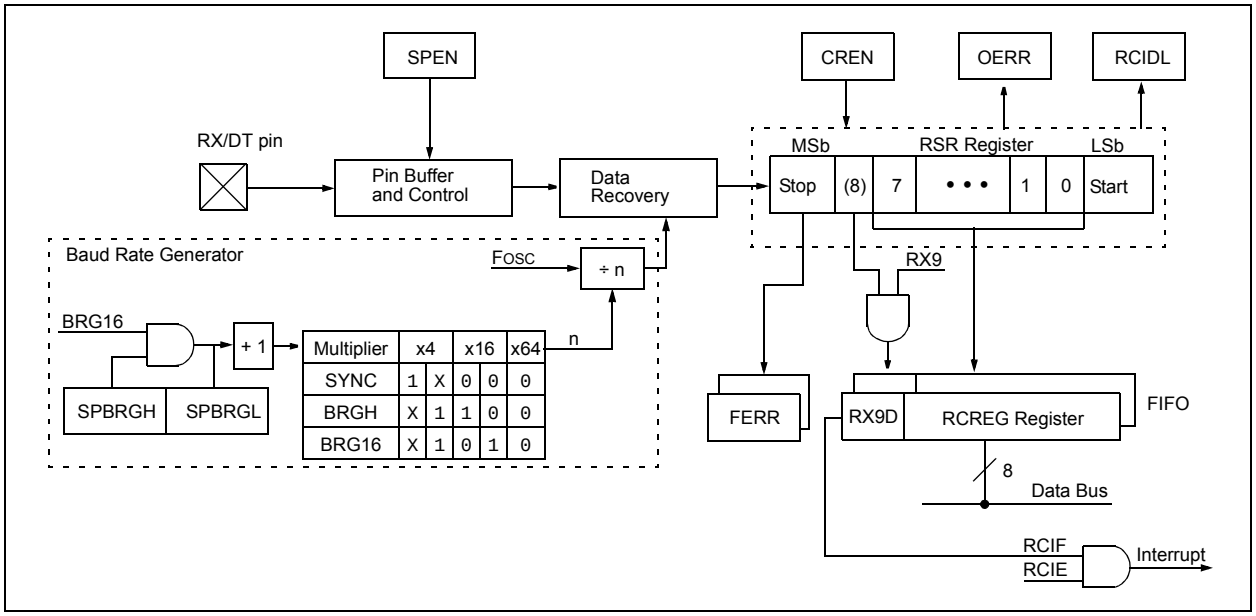


FIGURE 31-2: EUSART RECEIVE BLOCK DIAGRAM



The operation of the EUSART module is controlled through three registers:

- Transmit Status and Control (TXSTA)
- Receive Status and Control (RCSTA)
- Baud Rate Control (BAUDCON)

These registers are detailed in Register 31-1, Register 31-2 and Register 31-3, respectively.

The RX and CK input pins are selected with the RXPPS and CKPPS registers, respectively. TX, CK, and DT output pins are selected with each pin's RxyPPS register. Since the RX input is coupled with the DT output in Synchronous mode, it is the user's responsibility to select the same pin for both of these functions when operating in Synchronous mode. The EUSART control logic will control the data direction drivers automatically.

31.2 Clock Accuracy with Asynchronous Operation

The factory calibrates the internal oscillator block output (INTOSC). However, the INTOSC frequency may drift as V_{DD} or temperature changes, and this directly affects the asynchronous baud rate. Two methods may be used to adjust the baud rate clock, but both require a reference clock source of some kind.

The first (preferred) method uses the OSCTUNE register to adjust the INTOSC output. Adjusting the value in the OSCTUNE register allows for fine resolution changes to the system clock source. See **Section 6.2.2.3 "Internal Oscillator Frequency Adjustment"** for more information.

The other method adjusts the value in the Baud Rate Generator. This can be done automatically with the Auto-Baud Detect feature (see **Section 31.4.1 "Auto-Baud Detect"**). There may not be fine enough resolution when adjusting the Baud Rate Generator to compensate for a gradual change in the peripheral clock frequency.

31.3 Register Definitions: EUSART Control

REGISTER 31-1: TX1STA: TRANSMIT STATUS AND CONTROL REGISTER

R/W-/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R-1/1	R/W-0/0
CSRC	TX9	TXEN(1)	SYNC	SENDB	BRGH	TRMT	TX9D
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **CSRC:** Clock Source Select bit
Asynchronous mode:
Don't care
Synchronous mode:
1 = Master mode (clock generated internally from BRG)
0 = Slave mode (clock from external source)

bit 6 **TX9:** 9-bit Transmit Enable bit
1 = Selects 9-bit transmission
0 = Selects 8-bit transmission

bit 5 **TXEN:** Transmit Enable bit(1)
1 = Transmit enabled
0 = Transmit disabled

bit 4 **SYNC:** EUSART Mode Select bit
1 = Synchronous mode
0 = Asynchronous mode

bit 3 **SENDB:** Send Break Character bit
Asynchronous mode:
1 = Send Sync Break on next transmission (cleared by hardware upon completion)
0 = Sync Break transmission completed
Synchronous mode:
Don't care

bit 2 **BRGH:** High Baud Rate Select bit
Asynchronous mode:
1 = High speed
0 = Low speed
Synchronous mode:
Unused in this mode

bit 1 **TRMT:** Transmit Shift Register Status bit
1 = TSR empty
0 = TSR full

bit 0 **TX9D:** Ninth bit of Transmit Data
Can be address/data bit or a parity bit.

Note 1: SREN/CREN overrides TXEN in Sync mode.

FIGURE 34-7: CLKOUT AND I/O TIMING

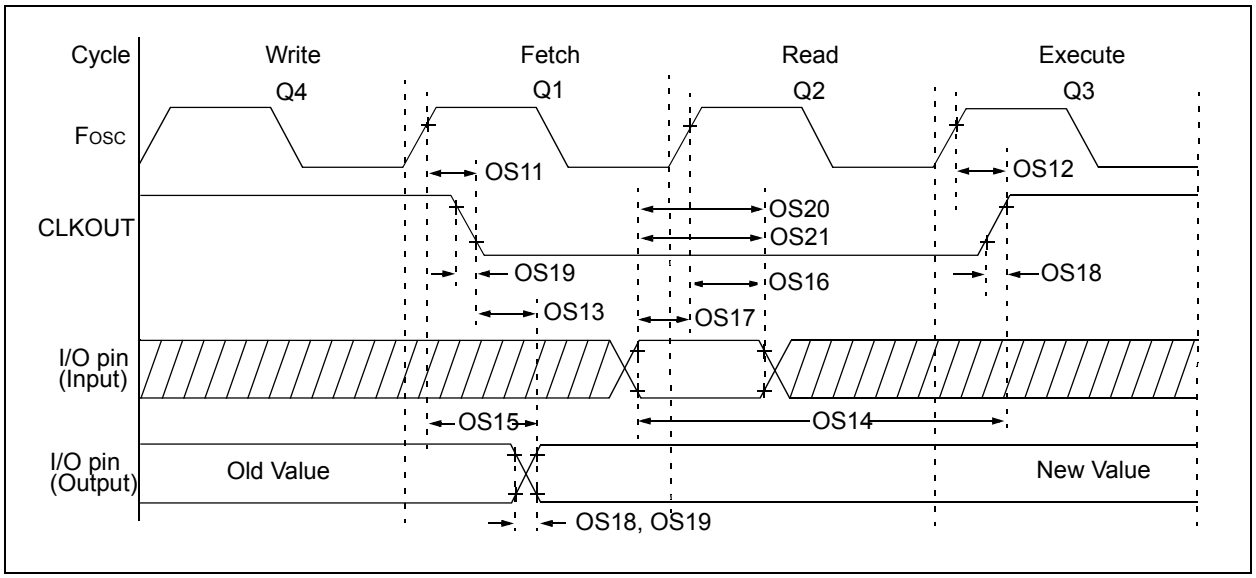


TABLE 34-10: CLKOUT AND I/O TIMING PARAMETERS

Standard Operating Conditions (unless otherwise stated)							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS11	TosH2ckL	FOSC↑ to CLKOUT↓ (1)	—	—	70	ns	3.3V ≤ VDD ≤ 5.0V
OS12	TosH2ckH	FOSC↑ to CLKOUT↑ (1)	—	—	72	ns	3.3V ≤ VDD ≤ 5.0V
OS13	TckL2ioV	CLKOUT↓ to Port out valid(1)	—	—	20	ns	
OS14	TioV2ckH	Port input valid before CLKOUT↑(1)	TOSC + 200 ns	—	—	ns	
OS15	TosH2ioV	Fosc↑ (Q1 cycle) to Port out valid	—	50	70*	ns	3.3V ≤ VDD ≤ 5.0V
OS16	TosH2ioI	Fosc↑ (Q2 cycle) to Port input invalid (I/O in hold time)	50	—	—	ns	3.3V ≤ VDD ≤ 5.0V
OS17	TioV2osH	Port input valid to Fosc↑ (Q2 cycle) (I/O in setup time)	20	—	—	ns	
OS18*	TioR	Port output rise time(2)	— —	40 15	72 32	ns	VDD = 1.8V 3.3V ≤ VDD ≤ 5.0V
OS19*	TioF	Port output fall time(2)	— —	28 15	55 30	ns	VDD = 1.8V 3.3V ≤ VDD ≤ 5.0V
OS20*	Tinp	INT pin input high or low time	25	—	—	ns	
OS21*	Tioc	Interrupt-on-change new input level time	25	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated.

Note 1: Measurements are taken in EXTRC mode where CLKOUT output is 4 x TOSC.

2: Slew rate limited.

TABLE 34-19: 8-BIT DIGITAL-TO-ANALOG CONVERTER (DAC1) SPECIFICATIONS

Operating Conditions (unless otherwise stated) V_{DD} = 3.0V, T_A = 25°C See **Section 35.0 "DC and AC Characteristics Graphs and Charts"** for operating characterization.							
Param No.	**Sym.**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
DAC01*	C_{LSB}	Step Size	—	$V_{DD}/256$	—	V	
DAC02*	C_{ACC}	Absolute Accuracy	—	—	± 1.5	LSb	
DAC03*	C_R	Unit Resistor Value (R)	—	600	—	Ω	
DAC04*	C_{ST}	Settling Time(1)	—	—	10	μs	

* These parameters are characterized but not tested.

Note 1: Settling time measured while DACR<7:0> transitions from '0x00' to '0xFF'.

TABLE 34-20: 5-BIT DIGITAL-TO-ANALOG CONVERTER (DAC2) SPECIFICATIONS

Operating Conditions (unless otherwise stated) V_{DD} = 3.0V, T_A = 25°C See **Section 35.0 "DC and AC Characteristics Graphs and Charts"** for operating characterization.							
Param No.	**Sym.**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
DAC05*	C_{LSB}	Step Size	—	$V_{DD}/32$	—	V	
DAC06*	C_{ACC}	Absolute Accuracy	—	—	± 0.5	LSb	
DAC07*	C_R	Unit Resistor Value (R)	—	6000	—	Ω	
DAC08*	C_{ST}	Settling Time(1)	—	—	10	μs	

* These parameters are characterized but not tested.

Note 1: Settling time measured while DACR<7:0> transitions from '0x00' to '0xFF'.

TABLE 34-21: ZERO CROSS PIN SPECIFICATIONS

Operating Conditions (unless otherwise stated) V_{DD} = 3.0V, T_A = 25°C							
Param. No.	**Sym.**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
ZC01	Z_{CPINV}	Voltage on Zero Cross Pin	—	0.75	—	V	
ZC02	Z_{CSRC}	Source current	—	600	—	μA	
ZC03	Z_{CSNK}	Sink current	—	600	—	μA	
ZC04	Z_{CISW}	Response Time Rising Edge	—	1	—	μs	
		Response Time Falling Edge	—	1	—	μs	
ZC05	Z_{COUT}	Response Time Rising Edge	—	1	—	μs	
		Response Time Falling Edge	—	1	—	μs	

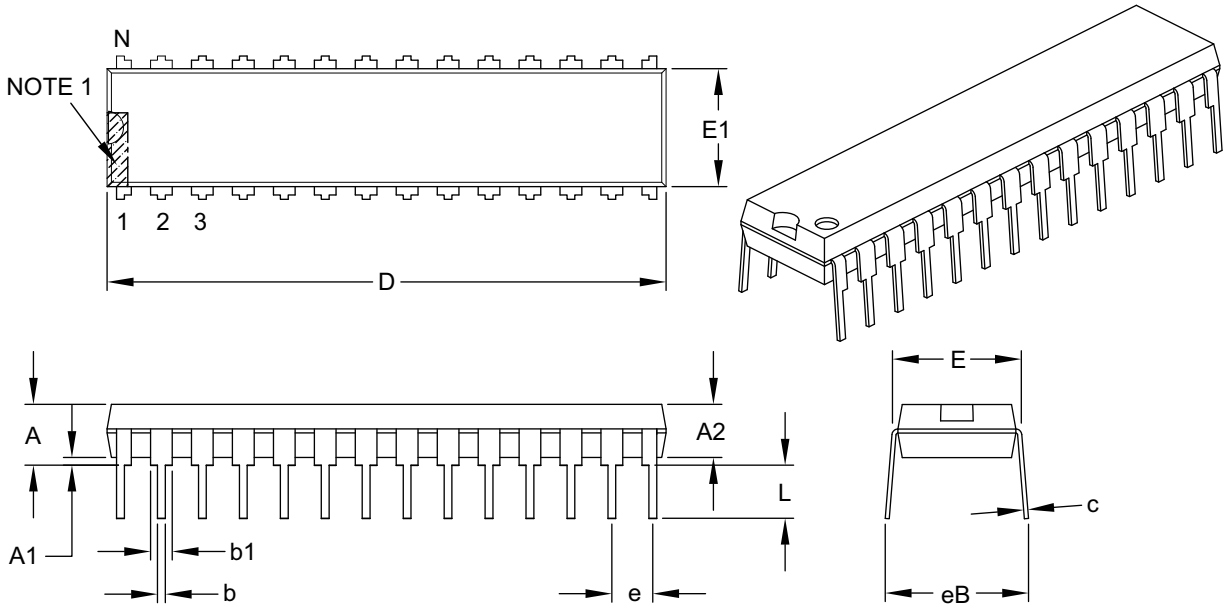
* These parameters are characterized but not tested.

37.2 Package Details

The following sections give the technical details of the packages.

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

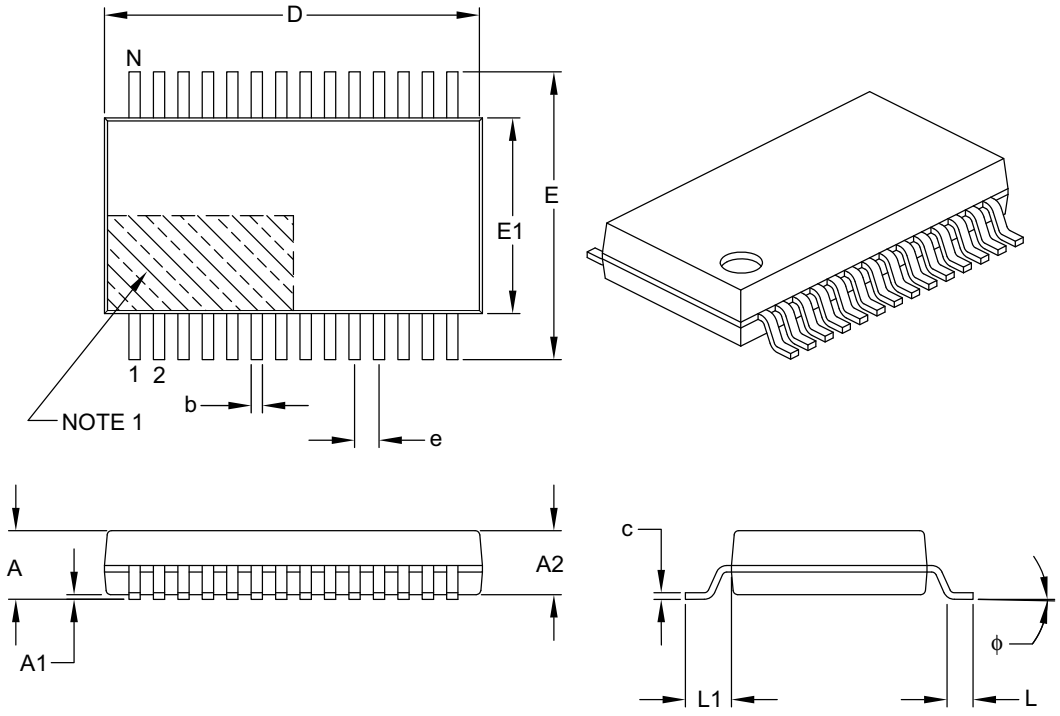
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	φ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B